EXPRESS MAIL LABEL NO. EV 398572737 US ATTORNEY DOCKET NO. N1085-00242 [TSMC2003-0464]

What is claimed is:

l	1.	A method for determining a target lifetime for a physical vapor deposition too	ı,
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- 2 comprising the steps of:
- 3 selecting criteria for a minimum accumulating rate of Δ wafers fabricated by Δ target life
- 4 for a target in the tool;
- recording actual values of Δ wafers fabricated by Δ target life for a target in the tool;
- 6 for a time period;
- 7 comparing a calculated, reported accumulating rate with a calculated, minimum
- 8 accumulating rate, and
- 9 checking the condition of the target in the tool, and deciding whether to replace the
- target, when the reported accumulating rate is less than the minimum accumulating rate.
- 1 2. The method of claim 1, and further comprising the steps of: recording the criteria in a
- 2 table for multiple targets in respective multiple ones of the tool; and
- 3 selecting the criteria by retrieving the criteria from the table.
- 1 3. The method of claim 1, and further comprising the step of: generating an alarm when the
- 2 reported accumulating rate is less than the minimum accumulating rate.
- 1 4. The method of claim 1 wherein, the step of selecting criteria for a minimum
- 2 accumulating rate, further comprises the step of selecting the criteria of thinnest wafers
- 3 fabricated by the tool for a minimum accumulating rate of Δ thinnest wafers fabricated by Δ
- 4 target life for a target in the tool.
- 1 5. The method of claim 4, and further comprising the step of: recording the criteria in a
- 2 table for multiple targets in respective multiple ones of the tool.
- 1 6. The method of claim 4, and further comprising the step of: generating an alarm when the
- 2 reported accumulating rate is less than the minimum accumulating rate.

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- 1 7. The method of claim 1 wherein, the step of comparing a calculated reported accumulating
- 2 rate with a calculated, minimum accumulating rate, further comprises the step of comparing a
- 3 graph of the reported accumulating rate with a slope of the minimum accumulating rate for one
- 4 KWH of tool power.
- 1 8. The method of claim 7, and further comprising the step of: generating an alarm when the
- 2 graph has a slope that is less than the slope of the minimum accumulating rate for one KWH of
- 3 tool power.
- 1 9. The method of claim 7, and further comprising the step of: recording the criteria in a
- 2 table for multiple targets in respective multiple ones of the tool.
- 1 10. The method of claim 7, and further comprising the step of: generating an alarm when the
- 2 reported accumulating rate is less than the minimum accumulating rate.
- 1 11. The method of claim 7 wherein, the step of selecting criteria for a minimum
- 2 accumulating rate, further comprises the step of selecting the criteria of thinnest wafers
- 3 fabricated by the tool for a minimum accumulating rate of Δ thinnest wafers fabricated by Δ
- 4 target life for a target in the tool.
- 1 12. A system for determining a lifetime of a target for a physical vapor deposition tool,
- 2 comprising:
- a mapping table of criteria for a minimum accumulating rate of Δ wafers fabricated by Δ
- 4 target life for a target in the tool;
- 5 a database recording Δ wafers fabricated by Δ target life for a target in the tool;
- a computer retrieving the criteria from the mapping table and entering the criteria in the
- 7 database; and
- 8 the tool reporting Δ wafers fabricated by Δ target life for a target in the tool for
- 9 comparison with the criteria.